2SC5838

Silicon NPN epitaxial planar type

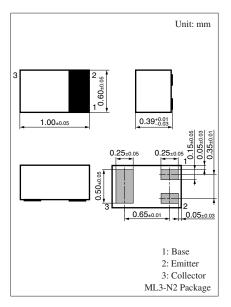
For UHF band low-noise amplification

■ Features

Suitable for high-density mounting and downsizing of the equipment for Ultraminiature leadless package
 0.6 mm × 1.0 mm (height 0.39 mm)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V _{CBO}	15	V	
Collector-emitter voltage (Base open)	V _{CEO}	10	V	
Emitter-base voltage (Collector open)	V_{EBO}	2	V	
Collector current	I_C	80	mA	
Collector power dissipation	P _C	100	mW	
Junction temperature	T_{j}	125	°C	
Storage temperature	T _{stg}	-55 to +125	°C	

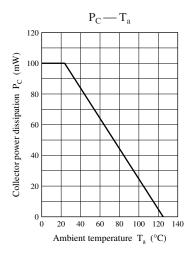


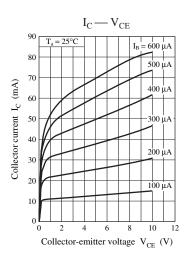
Marking symbol: 1F

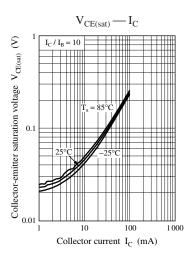
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

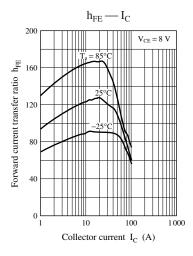
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_C = 10 \mu\text{A}, I_E = 0$	15			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_C = 100 \ \mu A, I_B = 0$	10			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 10 \text{ V}, I_{E} = 0$			1	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 2 \text{ V}, I_C = 0$			1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}$	110		250	_
Forward transfer gain	S _{21e} 2	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 800 \text{ MHz}$	7.5	10.0		dB
Noise figure	NF	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 800 \text{ MHz}$		1.7		dB
Maximum unilateral power gain	G_{UM}	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 800 \text{ MHz}$		11.5		dB
Collector output capacitance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		0.9	1.2	pF
(Common base, input open circuited)						
Transition frequency	f_T	$V_{CE} = 8 \text{ V}, I_{C} = 20 \text{ mA}, f = 800 \text{ MHz}$	5.0	6.0		GHz

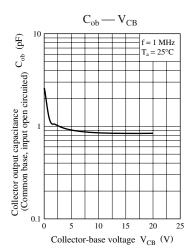
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.











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